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CERMET GOLD CONDUCTOR 8881-BA

A newly developed dense alloyed gold version of ESL 8881-B is designed for use on 96% alumina or on 4905-C multilayer dielectric. ESL 8881-BA exhibits strong adhesion to both alumina and 4905-C, high coverage, excellent wire bondability for aluminum wire, no center-line depression, and good line definition. For gold wirebonding, 8881-B is recommended.

HIGHLIGHTS OF 8881-BA ARE:

- Thin, very dense fired film
- Excellent printing
- Excellent wire bonding
- Fine line resolution
- 850°C firing temperature

PASTE DATA

RHEOLOGY:	Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, 10 rpm, ABZ spindle, 25.5°C±0.5°C)	275±25 Pa·s
BONDING MECHANISM:	MICRO-LOK®
SHELF LIFE: (at 25°C)	6 months

PROCESSING

SCREEN MESH/EMULSION:	325/25 µm
LEVELING TIME: (at 25°C)	5-10 minutes
DRYING AT 125°C:	10-15 minutes
OPTIMUM FIRING TEMPERATURE:	850°C
TIME AT PEAK:	10 minutes
RATE OF ASCENT/DESCENT:	60°C-100°C/minute
SUBSTRATE FOR CALIBRATION:	96% alumina

8881-BA 9710-C

ESL Affiliates
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See Caution and Disclaimer on other side.

THINNER: ESL 413

TYPICAL PROPERTIES

THICKNESS:	7-9 μm
RESISTIVITY:	< 5 mΩ/sq.
PRINTING RESOLUTION: (Line/Space)	75 μm/75 μm
SOLDERABILITY:	solderable with 80 Au/20 Sn alloy solder
ULTRASONIC Al WIRE BOND:	
Initial (25 μm Al wire):	> 8 grams
Aged (48 hours at 150°C):	> 6 grams

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